

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.00597	5.0	0.35492
	Lead alloy	Silver (Ag)	7440-22-4	0.00298	2.5	0.17746
	Lead alloy	Lead (Pb)	7439-92-1	0.11039	92.5	6.56609
Subtotal				0.11934	100	7.09847
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.36987	100.0	22
	Subtotal				0.36987	100
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02012	0.03	1.197
	Copper alloy	Iron (Fe)	7439-89-6	0.06708	0.1	3.99
	Copper alloy	Copper (Cu)	7440-50-8	66.99396	99.87	3,984.813
Subtotal				67.08116	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.09053	6.5	124.345
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.14592	16.0	306.08
	Filler	Silica fused	60676-86-0	22.835	71.0	1,358.23
	Flame retardant	Metal hydroxide		2.09053	6.5	124.345
Subtotal				32.16198	100	NaN
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.09953	100.0	5.92
	Subtotal				0.09953	100
Die		Lead Dioxide (PbO2)	1309-60-0	0.00111	0.66	0.066
	Doped silicon	Silicon (Si)	7440-21-3	0.16701	99.34	9.934
Subtotal				0.16812	100	10
Total				100	100	NaN

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